



100V 1.3mΩ TOLL N-Ch Power MOSFET

Features

- Ultra-low $R_{DS(ON)}$
- Low Gate Charge
- 100% UIS Tested, 100% R_g Tested
- Pb-free Lead Plating
- Halogen-free and RoHS-compliant

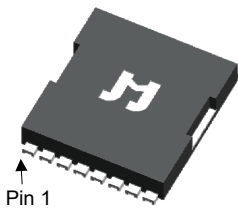
Product Summary

Parameter	Value	Unit
V_{DS}	100	V
$V_{GS(th_Typ)}$	2.8	V
$I_D (@ V_{GS} = 10V)^{(1)}$	411	A
$R_{DS(ON_Typ)} (@ V_{GS} = 10V)$	1.3	mΩ

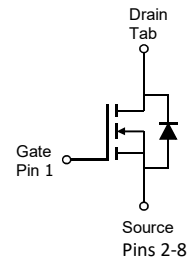
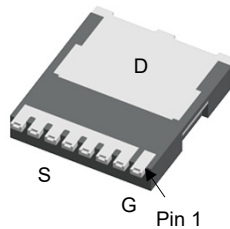
Applications

- Power Management in Telecom., Industrial Automation, CE
- Current/Voltage Switching in DC/DC & AC/DC Sub-systems
- Motor Driving or BMS in Power Tool, E-vehicle, Robotics

PowerJE®10x12 Top View



PowerJE®10x12 Bottom



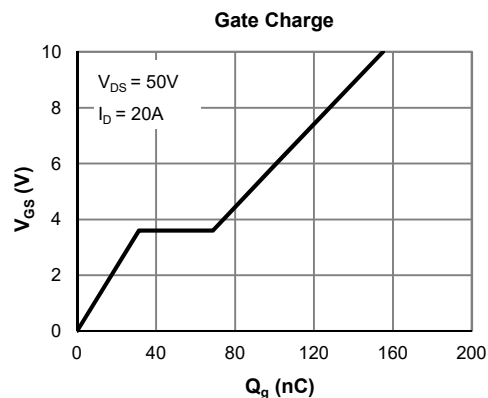
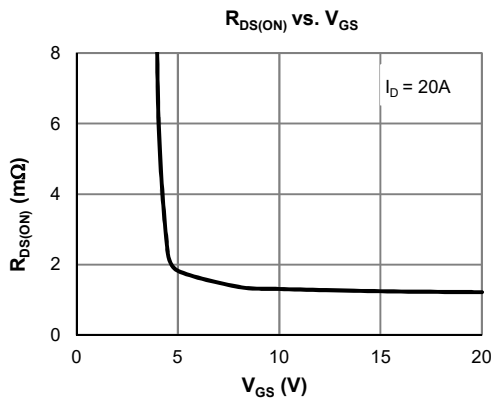
Ordering Information

Device	Package	# of Pins	Marking	MSL	T_J (°C)	Media	Quantity (pcs)
JMSH1001ATL-13	PowerJE®10x12 ⁽¹⁾	8	SH1001A	1	-55 to 175	13-inch Reel	2000

Note 1: PowerJE® is a registered trademark of JieJie Micro., its package outline is compatible to that of TO-LeadLess (TOLL).

Absolute Maximum Ratings (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DS}	100	V
Gate-to-Source Voltage	V_{GS}	±20	V
Continuous Drain Current ⁽²⁾	I_D	$T_C = 25^\circ\text{C}$	411
		$T_C = 100^\circ\text{C}$	290
Pulsed Drain Current ⁽³⁾	I_{DM}	1343	A
Avalanche Current ⁽⁴⁾	I_{AS}	50	A
Avalanche Energy ⁽⁴⁾	E_{AS}	1250	mJ
Power Dissipation ⁽⁵⁾	P_D	$T_C = 25^\circ\text{C}$	500
		$T_C = 100^\circ\text{C}$	250
Junction & Storage Temperature Range	T_J, T_{STG}	-55 to 175	°C



**Electrical Characteristics** (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

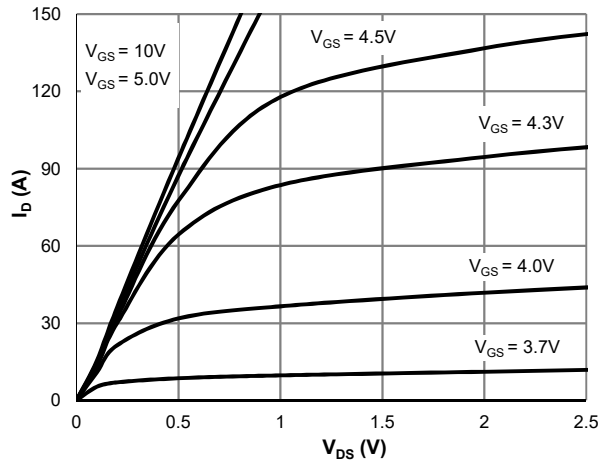
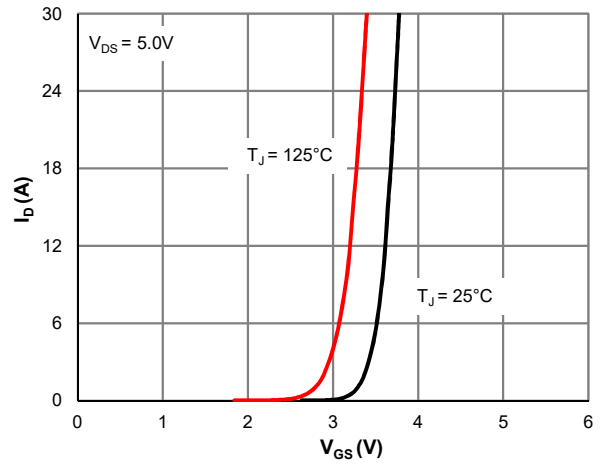
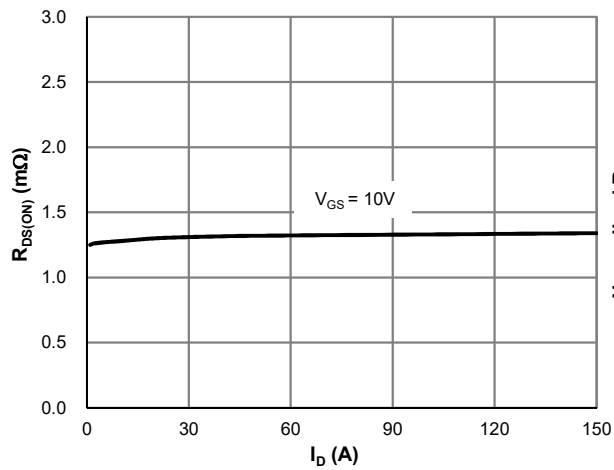
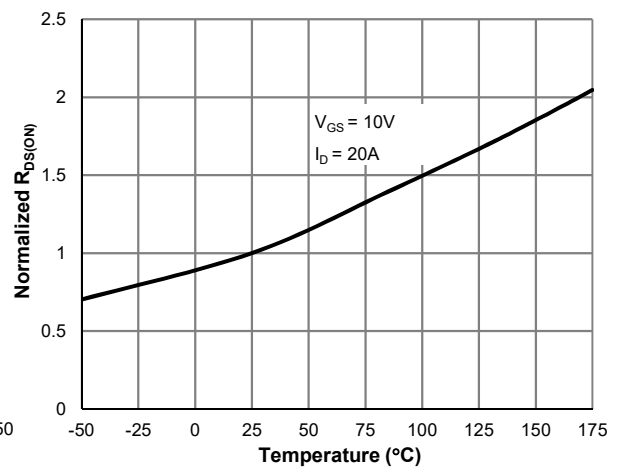
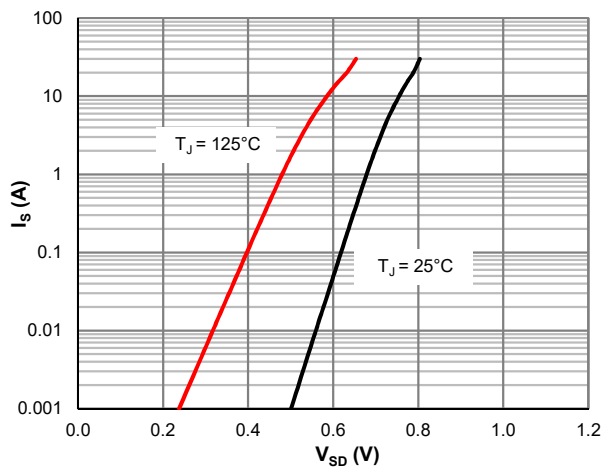
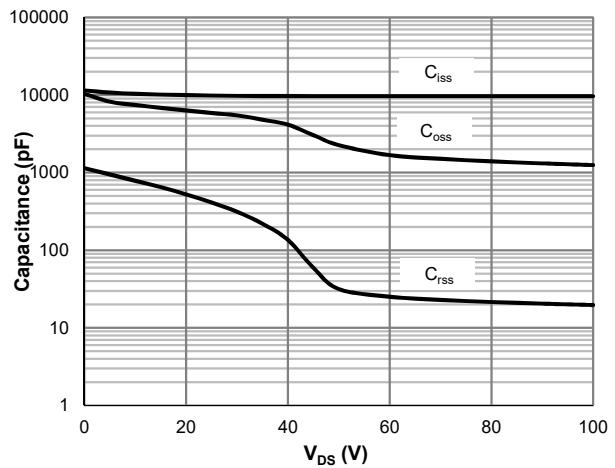
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
STATIC PARAMETERS						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	100			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 80\text{V}, V_{GS} = 0\text{V}$			1.0	μA
					5.0	
Gate-Body Leakage Current	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.0	2.8	4.0	V
Static Drain-Source ON-Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{V}, I_D = 20\text{A}$		1.3	1.6	m Ω
Forward Transconductance	g_{FS}	$V_{DS} = 5\text{V}, I_D = 20\text{A}$		94		S
Diode Forward Voltage	V_{SD}	$I_S = 1\text{A}, V_{GS} = 0\text{V}$		0.7	1.0	V
Diode Continuous Current	I_S	$T_C = 25^\circ\text{C}$			500	A
DYNAMIC PARAMETERS ⁽⁶⁾						
Input Capacitance	C_{iss}	$V_{GS} = 0\text{V}, V_{DS} = 50\text{V}, f = 1\text{MHz}$		9623		pF
Output Capacitance	C_{oss}			2091		pF
Reverse Transfer Capacitance	C_{rss}			32		pF
Gate Resistance	R_g	$V_{GS} = 0\text{V}, V_{DS} = 0\text{V}, f = 1\text{MHz}$		2.4		Ω
SWITCHING PARAMETERS ⁽⁶⁾						
Total Gate Charge (@ $V_{GS} = 10\text{V}$)	Q_g	$V_{GS} = 0 \text{ to } 10\text{V}$ $V_{DS} = 50\text{V}, I_D = 20\text{A}$		155		nC
Total Gate Charge (@ $V_{GS} = 6.0\text{V}$)	Q_g			101		nC
Gate Source Charge	Q_{gs}			31		nC
Gate Drain Charge	Q_{gd}			37		nC
Turn-On Delay Time	$t_{D(on)}$	$V_{GS} = 10\text{V}, V_{DS} = 50\text{V}$ $R_L = 2.5\Omega, R_{GEN} = 6\Omega$		34		ns
Turn-On Rise Time	t_r			67		ns
Turn-Off Delay Time	$t_{D(off)}$			145		ns
Turn-Off Fall Time	t_f			111		ns
Body Diode Reverse Recovery Time	t_{rr}		$I_F = 15\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$		76	
Body Diode Reverse Recovery Charge	Q_{rr}	$I_F = 15\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$		116		nC

Thermal Performance

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	35	45	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.20	0.30	$^\circ\text{C}/\text{W}$

Notes:

2. Computed continuous current assumes the condition of T_{J_Max} while the actual continuous current depends on the thermal & electro-mechanical application board design.
3. This single-pulse measurement was taken under $T_{J_Max} = 175^\circ\text{C}$.
4. This single-pulse measurement was taken under the following condition [$L = 1\text{mH}, V_{GS} = 10\text{V}, V_{DD} = 50\text{V}$] while its value is limited by $T_{J_Max} = 175^\circ\text{C}$.
5. The power dissipation P_D is based on $T_{J_Max} = 175^\circ\text{C}$.
6. This value is guaranteed by design hence it is not included in the production test.

Typical Electrical & Thermal Characteristics

Figure 1: Saturation Characteristics

Figure 2: Transfer Characteristics

Figure 3: $R_{DS(ON)}$ vs. Drain Current

Figure 4: $R_{DS(ON)}$ vs. Junction Temperature

Figure 5: Body-Diode Characteristics

Figure 6: Capacitance Characteristics

Typical Electrical & Thermal Characteristics

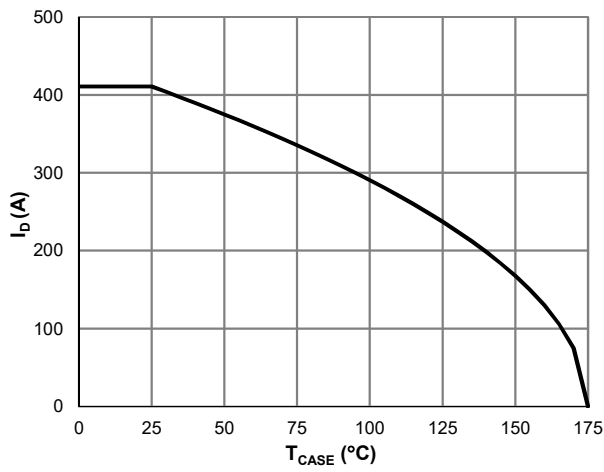


Figure 7: Current De-rating

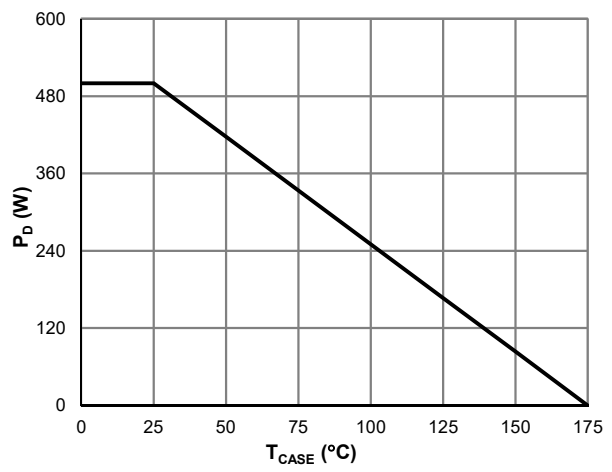


Figure 8: Power De-rating

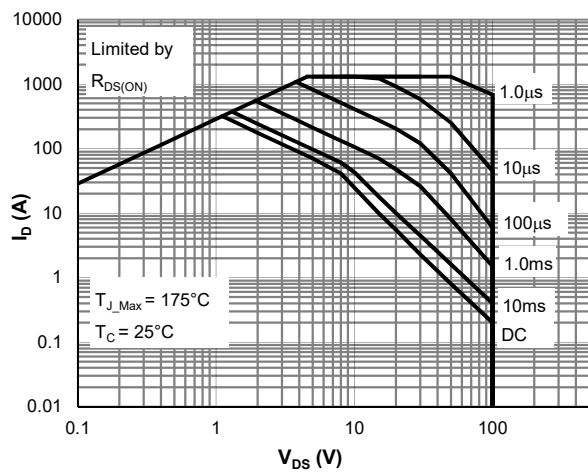


Figure 9: Maximum Safe Operating Area

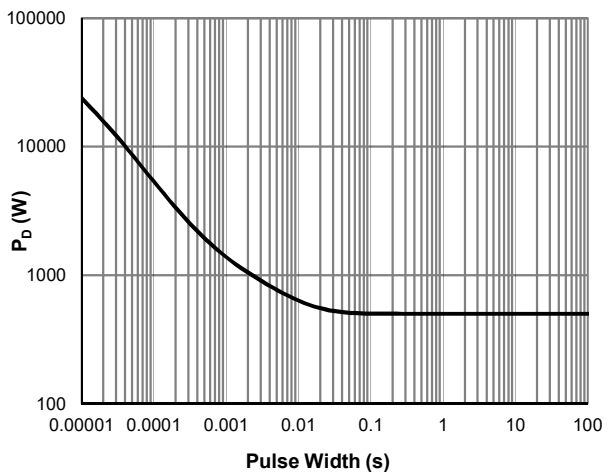


Figure 10: Single Pulse Power Rating, Junction-to-Case

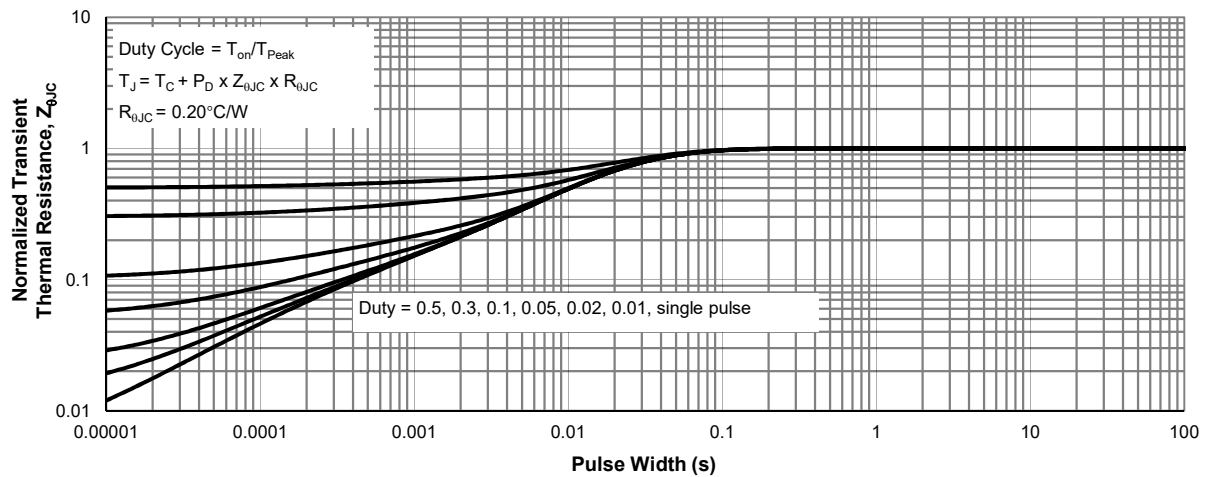
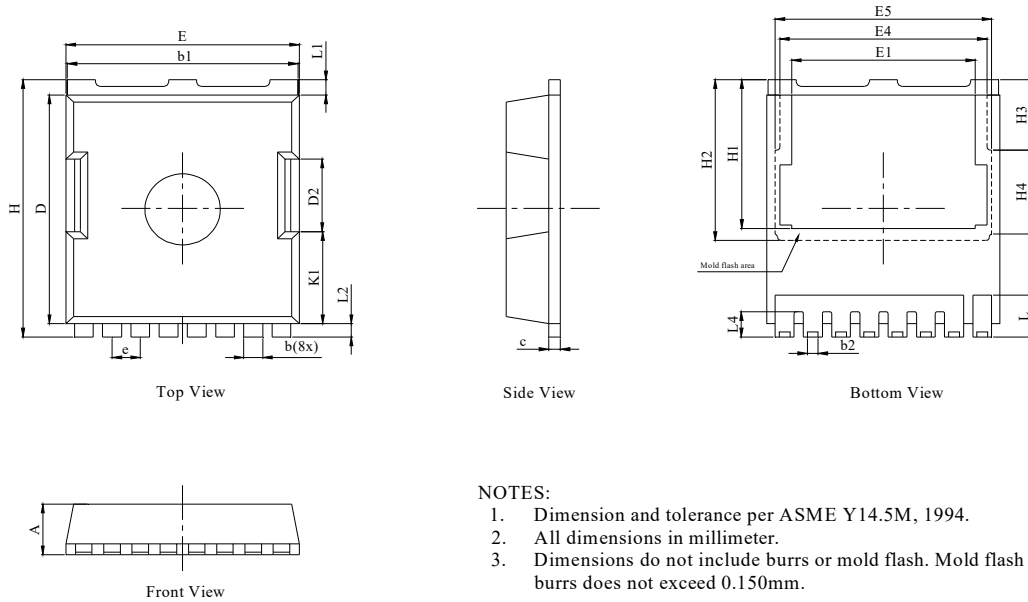


Figure 11: Normalized Maximum Transient Thermal Impedance

PowerJE® 10x12 Package Information
Package Outlines

NOTES:

1. Dimension and tolerance per ASME Y14.5M, 1994.
2. All dimensions in millimeter.
3. Dimensions do not include burrs or mold flash. Mold flash or burrs does not exceed 0.150mm.

DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	2.20	2.30	2.40
b	0.70	0.80	0.90
b1	9.70	9.80	9.90
b2	0.42	0.46	0.50
c	0.40	0.50	0.60
D	10.28	10.38	10.58
D2		3.30	
E	9.70	9.90	10.10
E1		7.80	
E4		8.80	
E5		9.20	
e	1.20 (BSC)		
H	11.48	11.68	11.88
H1	6.55	6.75	6.85
H2		7.30	
H3		3.20	
H4		3.80	
K1		4.18	
L	1.70	1.90	2.10
L1		0.70	
L2		0.60	
L4	1.00	1.15	1.30

Recommended Soldering Footprint
